

Description

μClamp® series are designed to protect sensitive electronics from damage or latch-up due to ESD and surge. They feature large cross-sectional area junctions for conducting high transient currents. They offer desirable characteristics for board level protection including fast response time, low operating and clamping voltage, and no device degradation.

μClamp1291PW features good ESD protection characteristics highlighted by low typical dynamic resistance, low peak ESD clamping voltage, and high ESD withstand voltage (+/-30kV contact and air per IEC 61000-4-2).

μClamp1291PW is in a DFN 1.0 x 0.6 x 0.55mm 2-Lead package. The small package gives the designer the flexibility to protect single lines in applications where arrays are not practical

Features

- High ESD withstand Voltage: +/-30kV (Contact) & +/-30kV(Air) per IEC 61000-4-2
- Protects one I/O or power line
- Low ESD clamping voltage
- Working voltage: +12V
- Low leakage current
- Solid-state silicon-avalanche technology

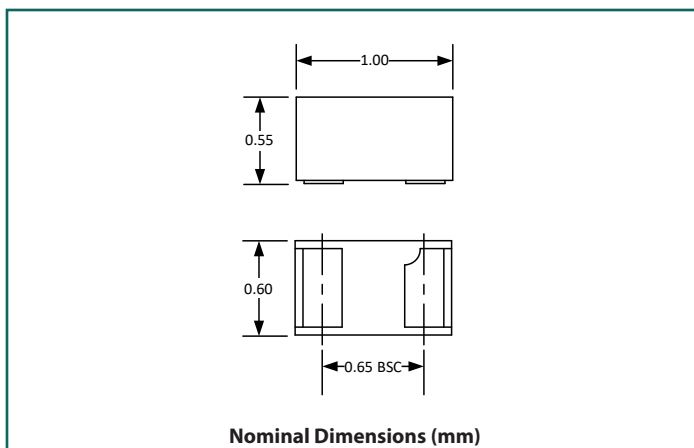
Mechanical Characteristics

- Package: DFN 1.0 x 0.6 x 0.55mm 2-Lead
- Pb-Free, Halogen Free, RoHS/WEEE Compliant
- Lead Finish: Pb-Free
- Marking: Marking Code
- Packaging: Tape and Reel

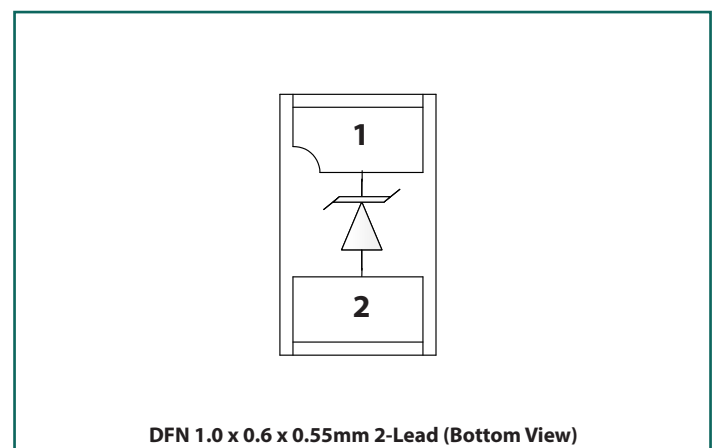
Applications

- Cellular Handsets & Accessories
- Notebooks & Handhelds
- Portable Instrumentation

Package Dimension



Schematic & Pin Configuration



Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power ($t_p = 8/20\mu s$)	P_{PK}	240	W
Peak Pulse Current ($t_p = 8/20\mu s$)	I_{PP}	10	A
ESD per IEC 61000-4-2 (Contact) ⁽¹⁾ ESD per IEC 61000-4-2 (Air) ⁽¹⁾	V_{ESD}	± 30 ± 30	kV
Operating Temperature	T_{OP}	-55 to +125	°C
Storage Temperature	T_{STG}	-55 to +150	°C

Electrical Characteristics (T=25°C unless otherwise specified)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Units
Reverse Stand-Off Voltage	V _{RWM}	Pin 1 to 2				12	V
Reverse Breakdown Voltage	V _{BR}	I _t = 1mA, Pin 1 to 2		13.3	14.6	17.5	V
Forward Voltage	V _F	I _F = 10mA, Pin 2 to Pin 1		0.4	0.78	1.1	V
Reverse Leakage Current	I _R	V _{RWM} = 12V, Pin 1 to 2			<5	500	nA
Clamping Voltage	V _C	tp =8/20μs	I _{PP} =1A, Pin 1 to 2		15	18	V
			I _{PP} =8A, Pin 1 to 2		19.3	23	
			I _{PP} =10A, Pin 1 to 2		20.8	24	
ESD Clamping Voltage ⁽²⁾	V _C	tp = 0.2/100ns (TLP), Pin 1 to 2	I _{TLP} = 4A		15.7		V
			I _{TLP} = 16A		19.1		
Dynamic Resistance ^{(2),(3)}	R _{DYN}	tp = 0.2/100ns (TLP), Pin 1 to 2			0.29		Ω
Junction Capacitance	C _J	V _R = 0V, f = 1MHz			75	90	pF

Notes:

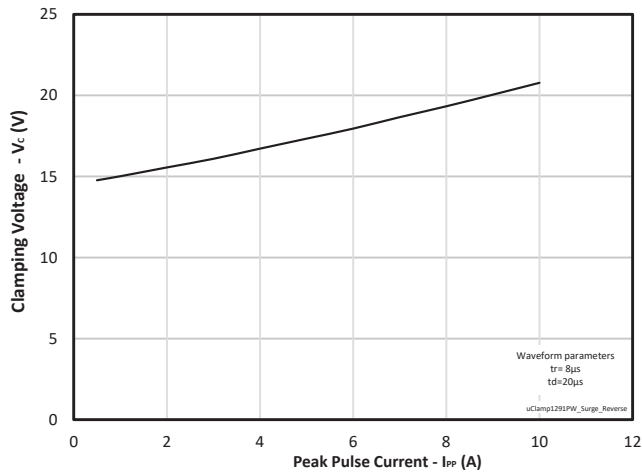
1) ESD gun return path connected to ESD ground plane.

2) Transmission Line Pulse Test (TLP) Settings: $t_p = 100ns$, $t_r = 0.2ns$, I_{TLP} and V_{TLP} averaging window: $t_1 = 70ns$ to $t_2 = 90ns$.

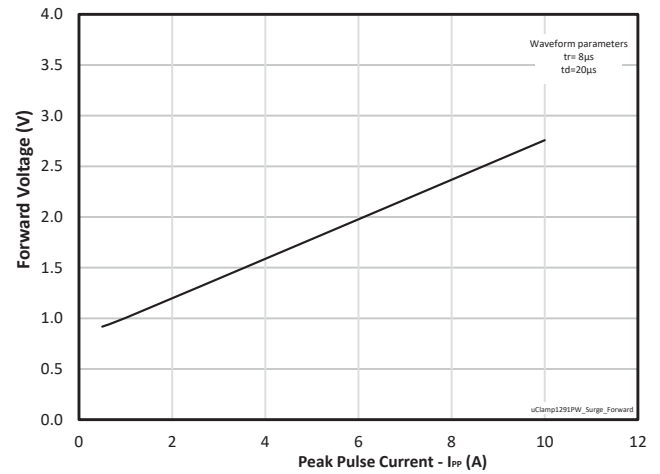
3) Dynamic resistance calculated from $I_{TLP} = 4A$ to $I_{TLP} = 16A$

Typical Characteristics

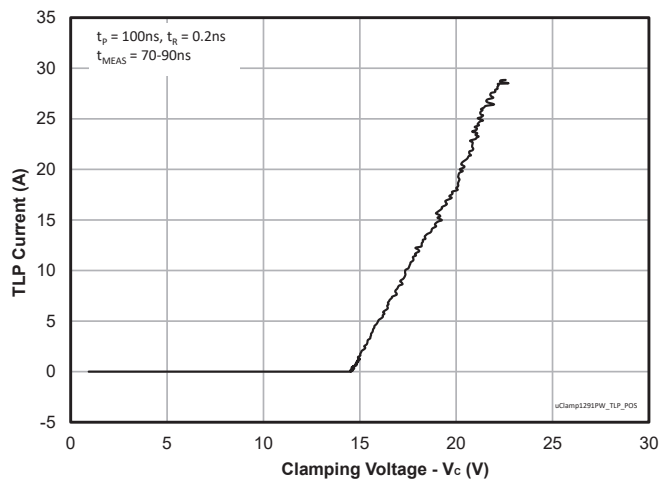
Clamping Voltage vs. Peak Pulse Current ($t_p=8/20\mu s$)



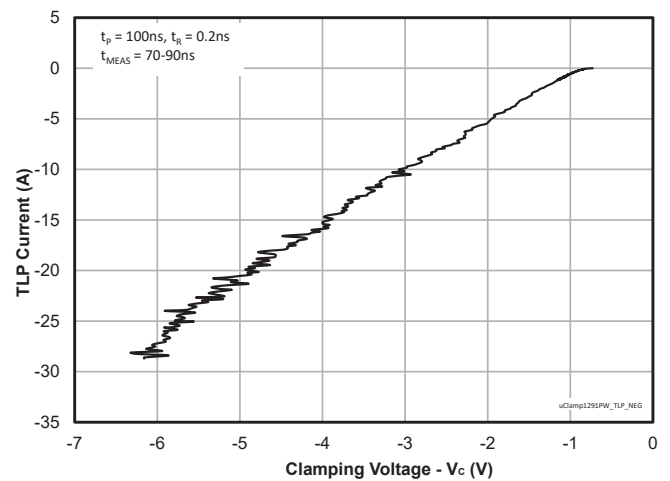
Forward Voltage vs. Peak Pulse Current ($t_p=8/20\mu s$)



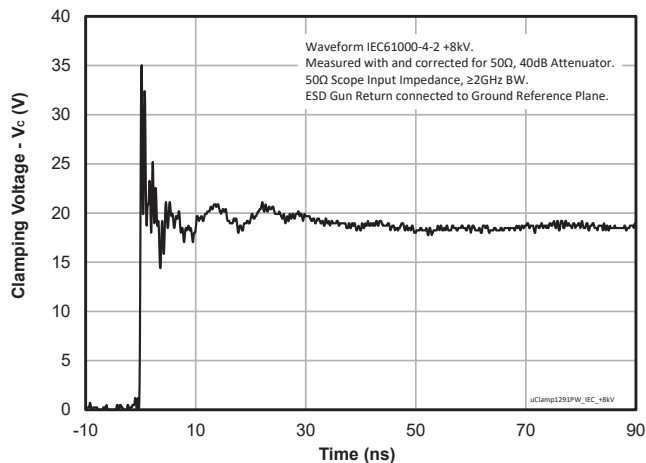
TLP Characteristic (Positive Pulse)



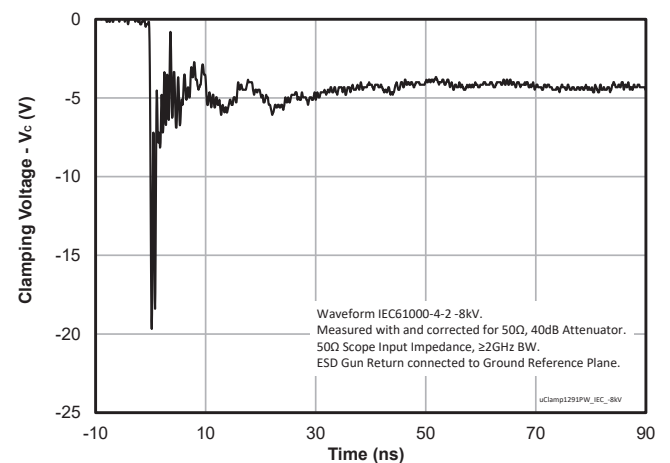
TLP Characteristic (Negative Pulse)



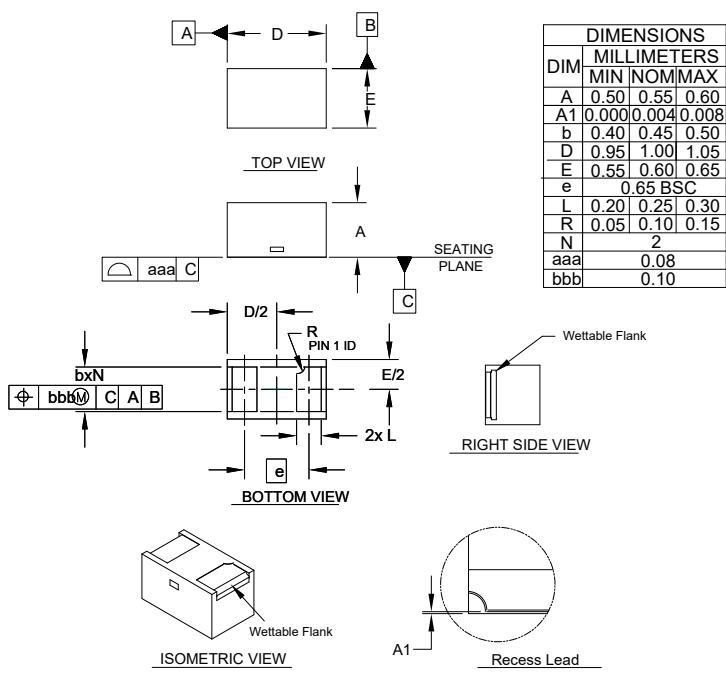
ESD Clamping (+8kV Contact per IEC 61000-4-2)



ESD Clamping (-8kV Contact per IEC 61000-4-2)

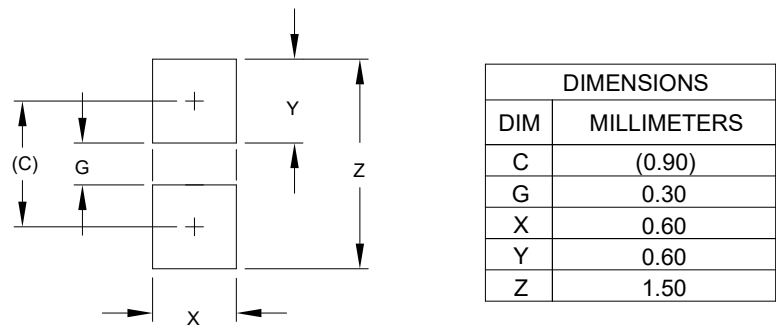


Outline Drawing - DFN 1.0 x 0.6 x 0.55mm 2-Lead



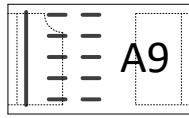
NOTES:
1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).

Land Pattern - DFN 1.0 x 0.6 x 0.55mm 2-Lead



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1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY.
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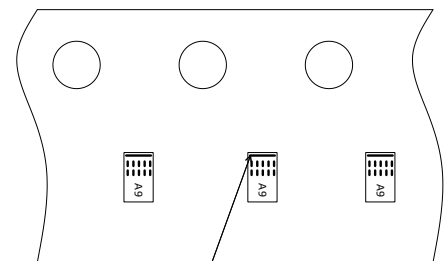
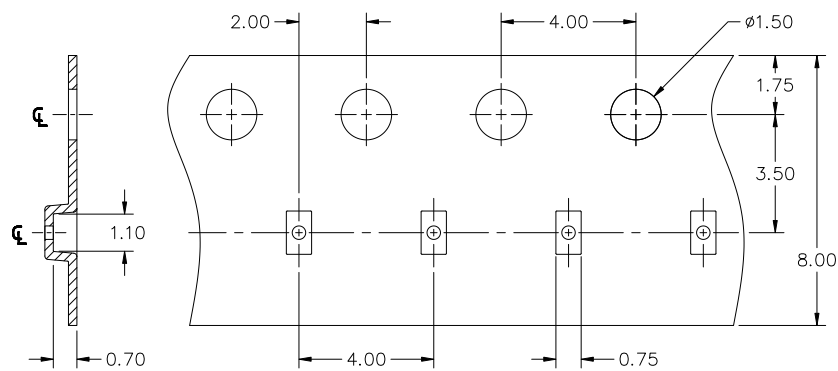
Marking Code



Notes:

1. Marking will also include line matrix date code
2. Bar indicates Pin 1 location

Tape and Reel Specification



Pin1 Location
(Bar Toward Sprocket Holes)

Ordering Information

Part Number	Qty per Reel	Reel Size
μ Clamp1291PW.C	3,000	7 Inch
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